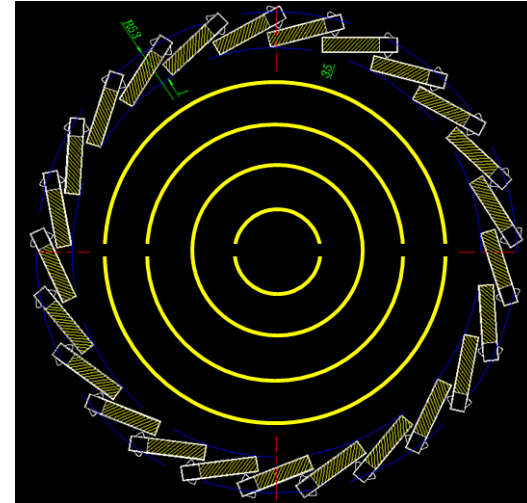
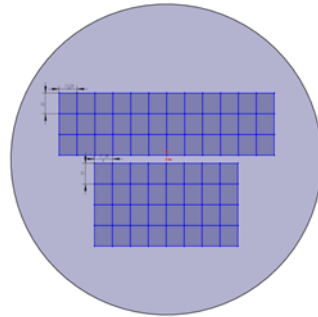


Vertex structure based on new base line

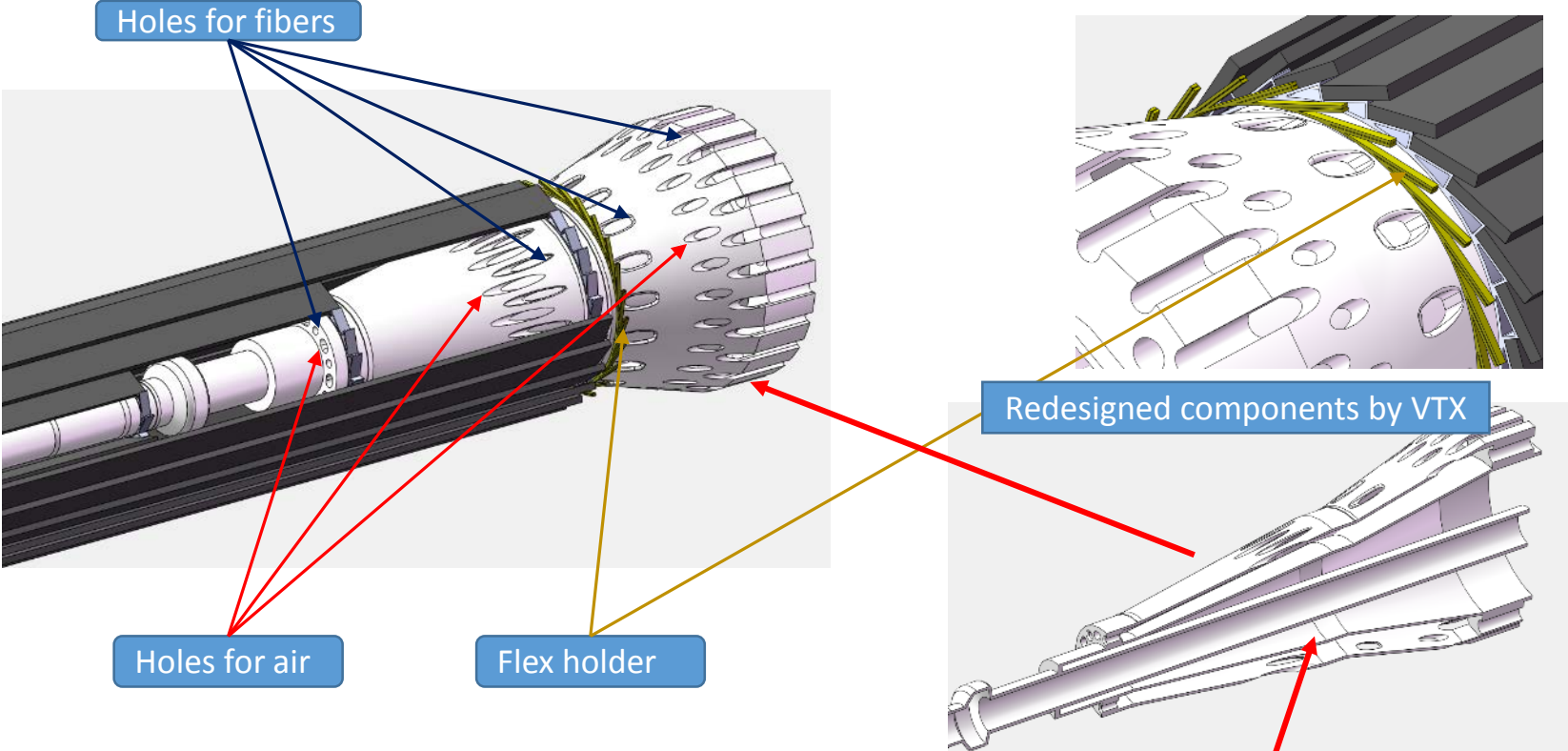
Preliminary stitching layout

Layout optimization

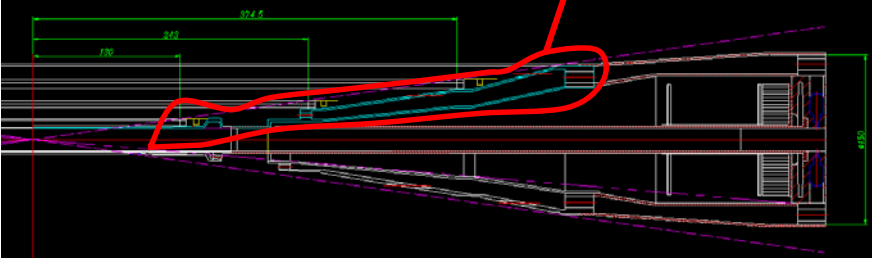
- R1=11mm, L1=160mm ;
 - Single chip dimension: 17.278*20 mm (X=8, Y=2)
- R2=16.5mm, L2=240mm ;
 - X=6, Y=3
- R3=22mm, L3= 320mm
 - X=8, Y=4
- R4= 27.5mm , L4 = 390
 - Difficult to fit into one wafer ?



Air channels and cables routing- outer barrel

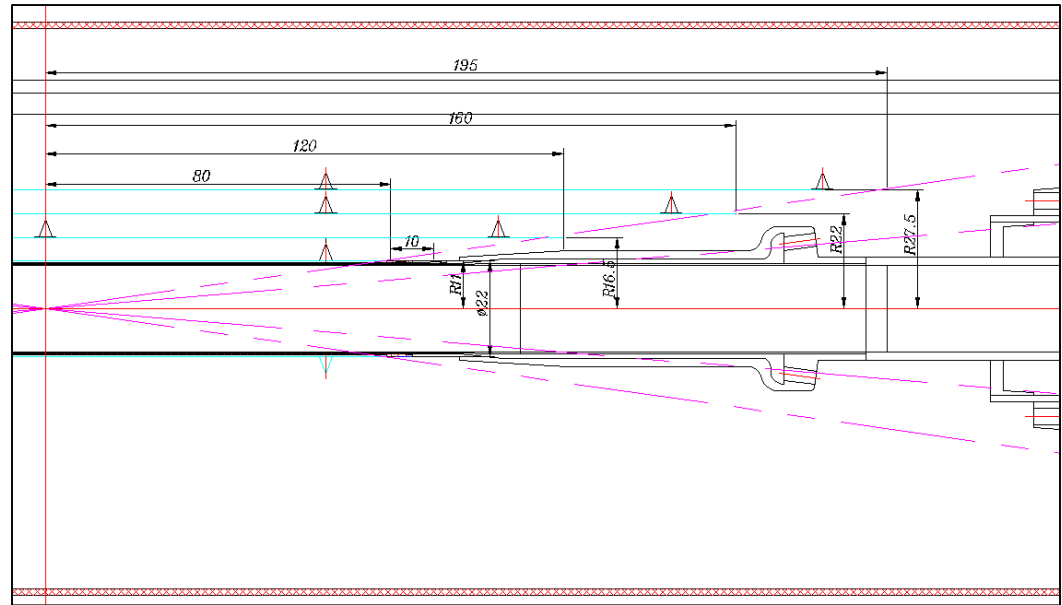
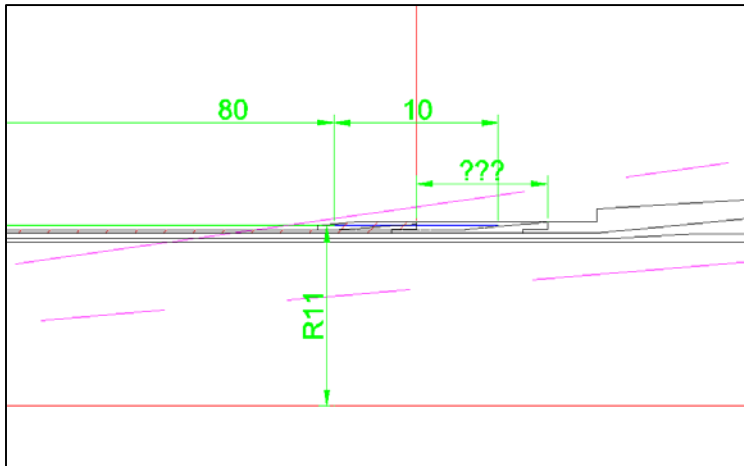


According to the current plan, assuming the flex will be switched to fiber where beyond and near the end of the ladder.

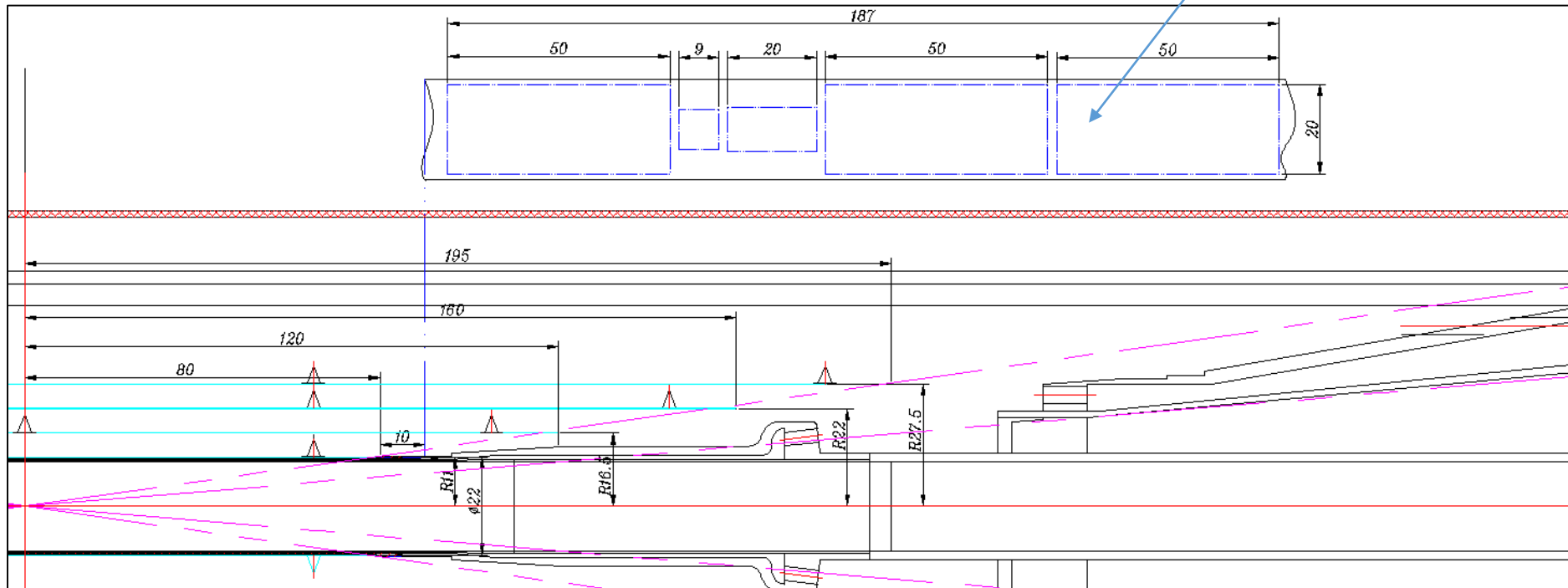
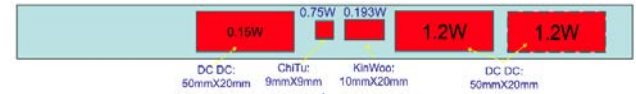


VTX-stiching 最内层尺寸与束流管对接？

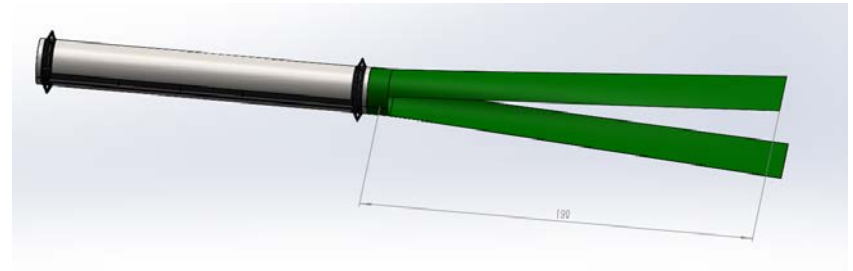
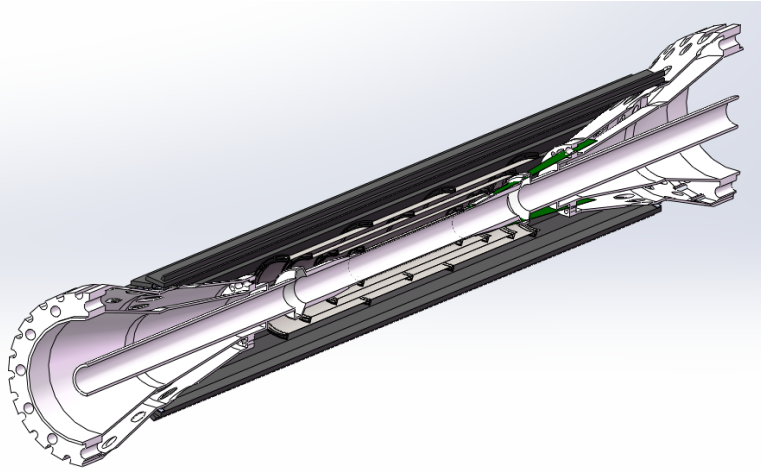
按当前layout：
最内层弯曲芯片R11 mm，
与外铍管段干涉。
外皮管可否适当延长？



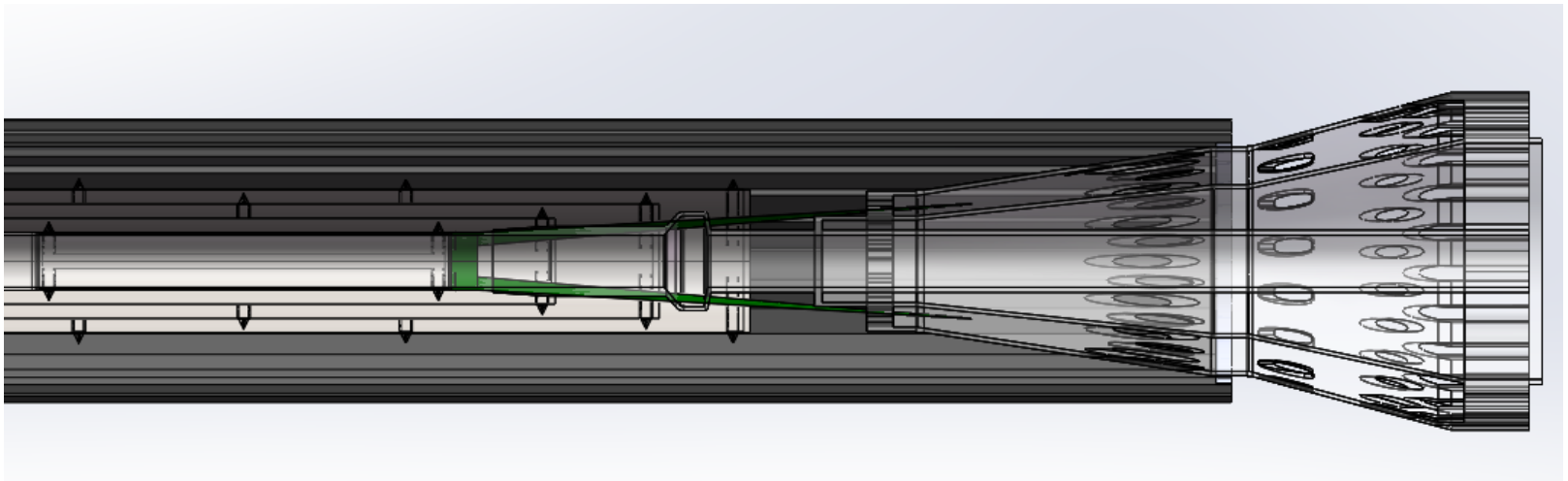
VTX-stiching 走线空间



VTX-stiching 走线空间

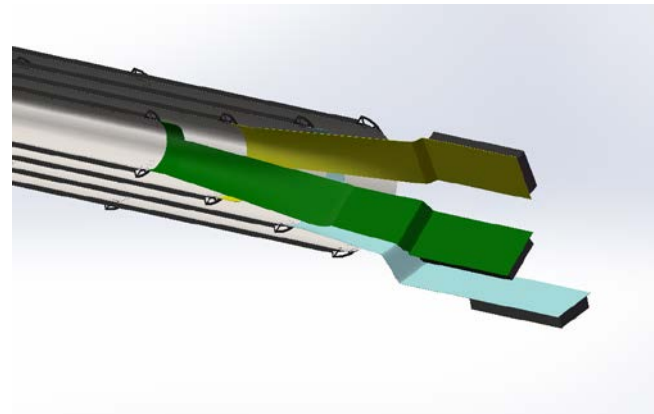
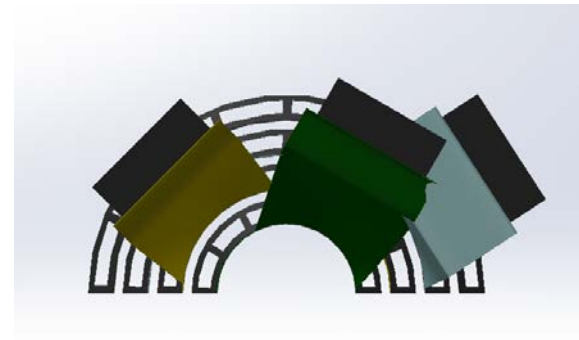
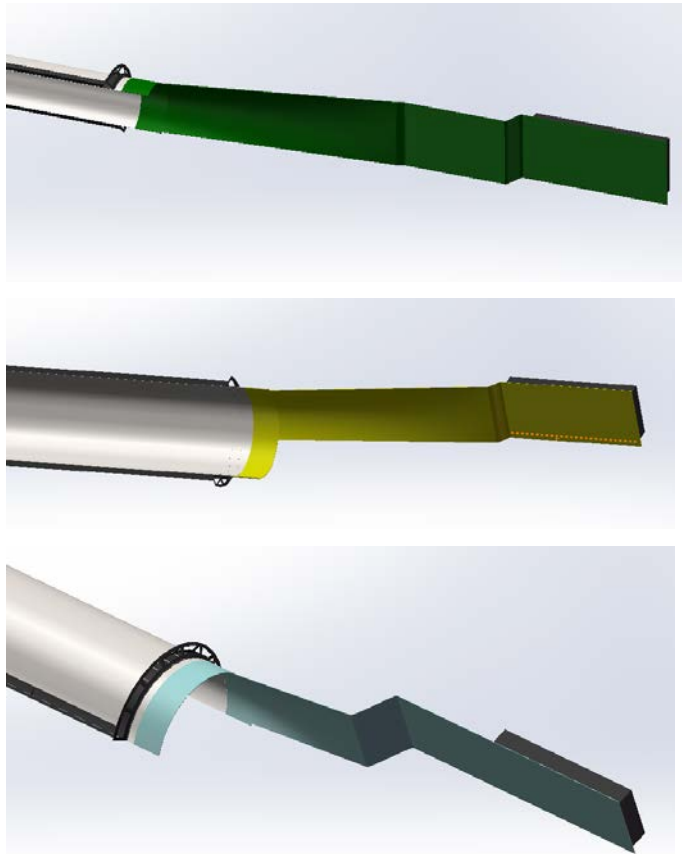


190x24 mm

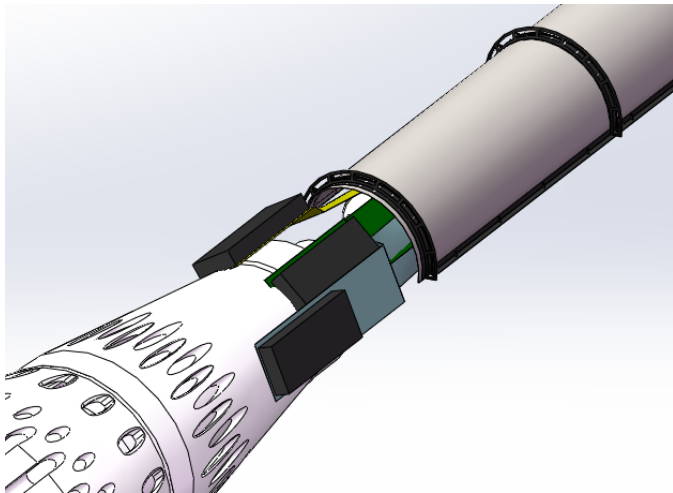
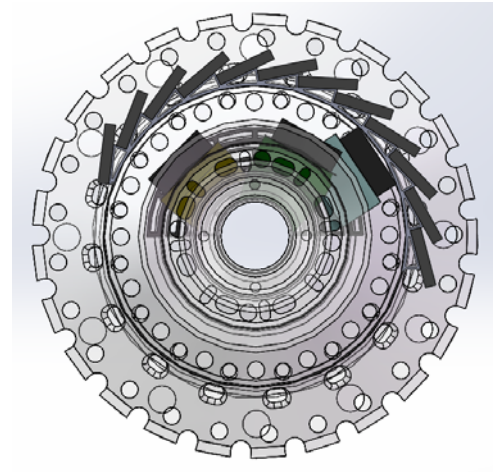
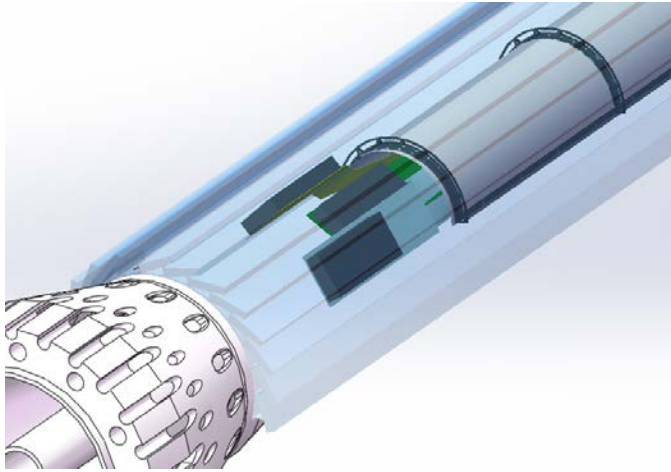


VTX-stiching 走线空间-update

试一个半圆上装一条flex，一个DC-DC 模块50x20x6.7 mm



VTX-stiching 走线空间-update



Stiching可用截面太小:

- 相邻层间flex周向有叠加、无间隙
- 4（示意3层）层的flex+DC-DC径向比较局促、贴近外桶
- 阻挡风道、支撑结构生根受阻